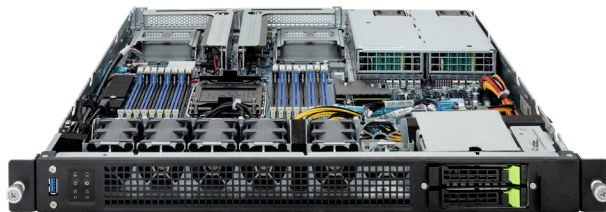


# E163-S30-AAB1

## 1U UP 2-Bay NVMe/SATA/SAS Edge Server



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### Features

- 4th Gen Intel® Xeon® Scalable Processors
- Intel® Xeon® CPU Max Series
- Single processor, LGA4677
- 8-Channel RDIMM DDR5 per processor, 16 x DIMMs
- Supports Intel® Optane™ Persistent Memory 300 series
- Dual ROM Architecture supported
- 1 x 1Gb/s LAN port (Intel® I210-AT)
- 1 x Dedicated management port
- 2 x 2.5" Gen4 NVMe/SATA hot-swappable bays
- Ultra-Fast M.2 with PCIe Gen3 x4 interface
- 2 x PCIe Gen5 x16 expansion slots
- 2 x OCP 3.0 Gen5 x16 mezzanine slots
- Dual 800W 80 PLUS Platinum redundant power supply

### Specification

<b>Dimensions</b>	1U (W438 x H43.5 x D520 mm)	<b>Rear I/O</b>	2 x USB 3.2 Gen1, 1 x Mini-DP, 1 x RJ45, 1 x MLAN
<b>Motherboard</b>	MS33-DC0	<b>Backplane I/O</b>	PCIe Gen4 x4 or SATA 6Gb/s or SAS 12Gb/s
<b>CPU</b>	4th Generation Intel® Xeon® Scalable Processors Intel® Xeon® CPU Max Series Intel® Xeon® Platinum Processor, Intel® Xeon® Gold Processor, Intel® Xeon® Silver Processor CPU TDP up to 350W	<b>TPM</b>	1 x TPM header with SPI interface (Optional TPM2.0 kit: CTM010)
<b>Socket</b>	1 x LGA 4677 (Socket E)	<b>Power Supply</b>	Dual 800W 80 PLUS Platinum redundant power supply AC Input: 100-240V
<b>Chipset</b>	Intel® C741 Chipset	<b>System Management</b>	Aspeed® AST2600 management controller GIGABYTE Management Console (AMI MegaRAC SP-X)
<b>Memory</b>	8-Channel DDR5 memory, 16 x DIMM slots RDIMM modules up to 128GB supported 3DS RDIMM modules up to 256GB supported Memory speed: Up to 4800 MHz (1DPC), 4400 MHz (2DPC)	<b>OS Compatibility</b>	Windows Server 2019 / 2011 RHEL 8.4 / 8.5 / 8.6 / 8.7 / 9.0 / 9.1 ( x64) SLES 15 SP3 / 15 SP4 ( x64) Ubuntu 22.04 LTS / 22.04.1 LTS (x64) VMware ESXi 7.0 Update 3i / 8.0
<b>LAN</b>	1 x 1Gb/s LAN ports (1 x Intel® I210-AT) Supported NCSI function 1 x 10/100/1000 management LAN	<b>System Fans</b>	5 x 40x40x56mm (30,000rpm)
<b>Video</b>	Integrated in Aspeed AST2600 2D Video Graphic Adapter with PCIe bus interface 1920x1200@60Hz 32bpp, DDR4 SDRAM	<b>Operating Properties</b>	Operating temperature: 10°C to 35°C Operating humidity: 8-80% (non-condensing) Non-operating temperature: -40°C to 60°C Non-operating humidity: 20%-95% (non-condensing)
<b>Storage</b>	2 x 2.5" Gen4 NVMe/SATA hot-swappable bays SAS card is required for SAS devices support	<b>Packaging Content</b>	1 x E163-S30, 1 x CPU heatsink, 3 x Carrier clips, 1 x Mini-DP to D-Sub cable Packaging Dimensions: 782 x 588 x 212 mm
<b>RAID</b>	Intel® SATA RAID 0/1/10/5	<b>Reference Numbers</b>	Barebone package: 6NE163S30DR000AAB1* - Motherboard: 9MS33DC0UR-000 - CPU heatsink: 25ST1-4Z3200-S7R - Front panel board: 9CFP1000NR-00 - Back plane board: 9CBP2023NR-00 - Mini-DP to D-Sub cable: 25CRN-200801-K1R - Power supply: 25EP0-208004-L0S
<b>Expansion Slots</b>	2 x PCIe Gen5 x16 FHHL slots 2 x PCIe Gen5 x16 OCP 3.0 slots - Supporte NCSI function 1 x M.2 slot (M-key, PCIe Gen3 x4, NGFF-2280/22110)		
<b>Front I/O</b>	1 x USB 3.2 Gen1		



Learn more about GIGABYTE server solutions, visit [www.gigabyte.com/Enterprise](http://www.gigabyte.com/Enterprise)

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